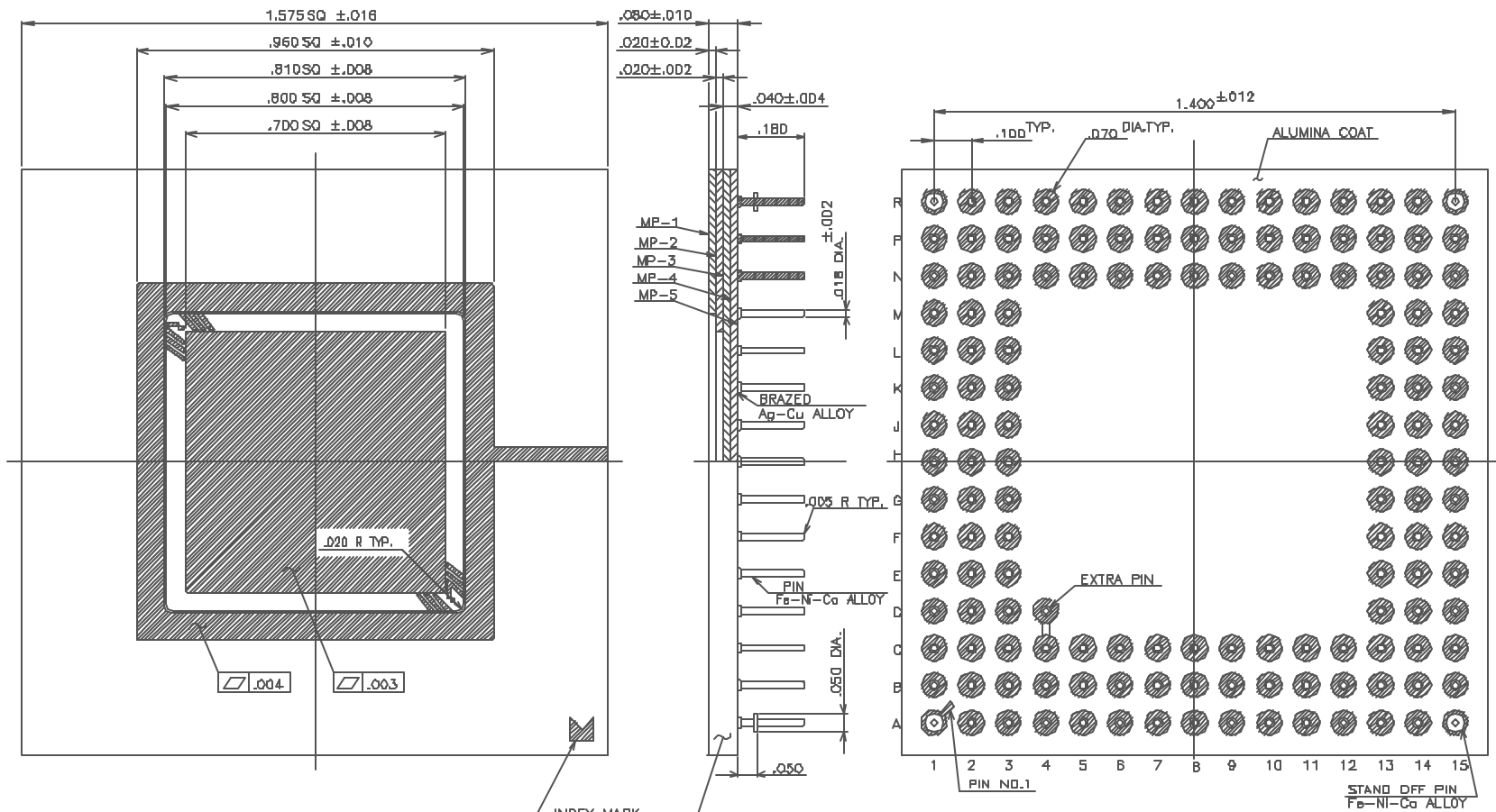


SSM P/N CPG14434



- NOTES**
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: B/F NO. 18, 19, 54, 55, 90, 91, 126, 127 ----- 230mOHMS MAX.
B/F NO. 1, 37, 73, 109, 9, 30, 44, 60, 81, 102, 117, 138 ----- 250mOHMS MAX.
THE OTHERS ----- 800mOHMS MAX.
 6. OPEN SHORT TEST TO BE PERFORMED ON ALL PINS.

MODIFICATION					NAME	145 PIN GRID ARRAY PACKAGE	TOLEANCE	PB145S499-1		S=0
REDRAWN					SCALE	5 / 1	±.005	DRAWN	CHECKED	APPROVED
CHANGED					MATERIAL	AS INDICATED	±.005	N.J.	A.F./T.A.	M.K.
DATE					DATE					DATE
					KYOCERA CORPORATION KYOTO JAPAN			DRAWING NO.		SHEET
								KD-P86499-B		1 / 3



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